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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	F ² MC-16FX
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, LINbus, SCI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	37
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb96f612rbpmc-gse1



Built-in On Chip Debugger (OCD)

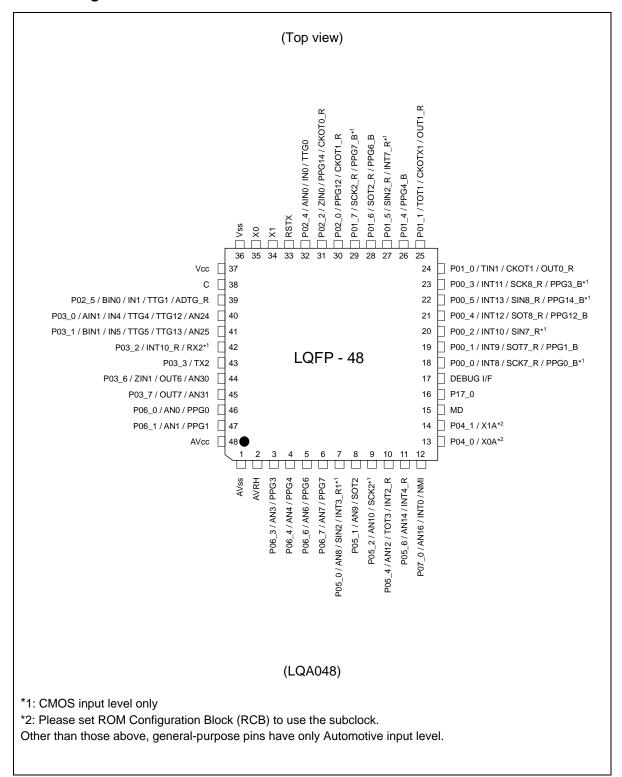
- One-wire debug tool interface
- Break function:
 - ☐ Hardware break: 6 points (shared with code event)
 - □ Software break: 4096 points
- Event function
 - □ Code event: 6 points (shared with hardware break)
 - □ Data event: 6 points
 - □ Event sequencer: 2 levels + reset
- Execution time measurement function
- Trace function: 42 branches
- Security function

Flash Memory

- Dual operation flash allowing reading of one Flash bank while programming or erasing the other bank
- Command sequencer for automatic execution of programming algorithm and for supporting DMA for programming of the Flash Memory
- Supports automatic programming, Embedded Algorithm
- Write/Erase/Erase-Suspend/Resume commands
- A flag indicating completion of the automatic algorithm
- Erase can be performed on each sector individually
- Sector protection
- Flash Security feature to protect the content of the Flash
- Low voltage detection during Flash erase or write



3. Pin Assignment

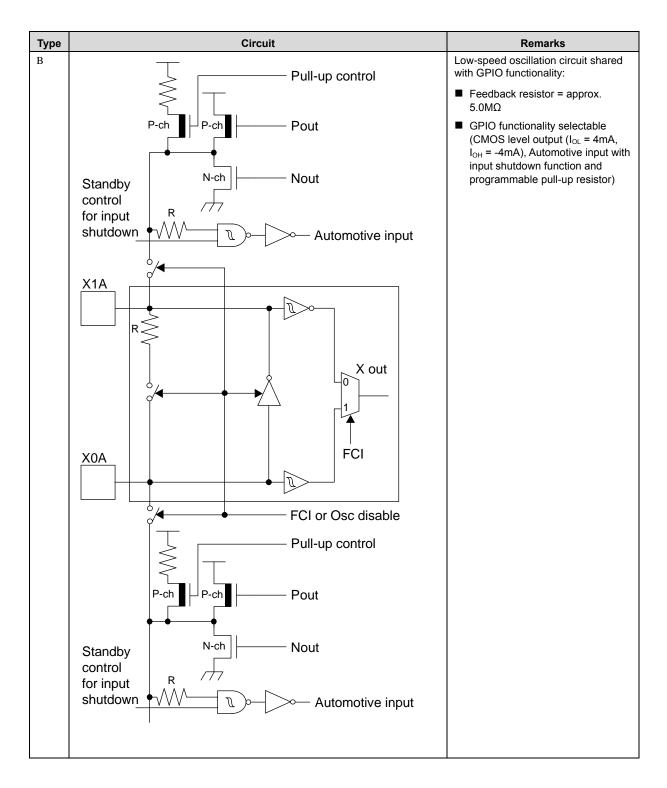




Pin No.	I/O Circuit Type*	Pin Name
33	С	RSTX
34	A	X1
35	A	Х0
36	Supply	Vss
37	Supply	Vcc
38	F	С
39	Н	P02_5 / BIN0 / IN1 / TTG1 / ADTG_R
40	К	P03_0 / AIN1 / IN4 / TTG4 / TTG12 / AN24
41	К	P03_1 / BIN1 / IN5 / TTG5 / TTG13 / AN25
42	M	P03_2 / INT10_R / RX2
43	Н	P03_3 / TX2
44	К	P03_6 / ZIN1 / OUT6 / AN30
45	К	P03_7 / OUT7 / AN31
46	К	P06_0 / AN0 / PPG0
47	К	P06_1 / AN1 / PPG1
48	Supply	AVcc

^{*:} See I/O Circuit Type" for details on the I/O circuit types.







Туре	Circuit	Remarks
С	R Hysteresis inputs	CMOS hysteresis input pin
F	P-ch N-ch	Power supply input protection circuit
G	P-ch N-ch	 A/D converter ref+ (AVRH) power supply input pin with protection circuit Without protection circuit against V_{cc} for pins AVRH
Н	Pull-up control P-ch P-ch P-ch Nout R Automotive input	 ■ CMOS level output ■ (I_{OL} = 4mA, I_{OH} = -4mA) ■ Automotive input with input shutdown function ■ Programmable pull-up resistor



Туре	Circuit	Remarks
О		■ Open-drain I/O
		■ Output 25mA, Vcc = 2.7V
		■ TTL input
	Standby control for input shutdown	



8. RAMstart Addresses

Devices	Bank 0 RAM Size	RAMSTART0
CY96F612	4KB	00:7200 _H
CY96F613, CY96F615	10KB	00:5A00 _н

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Vector Number	Offset in Vector Table	Vector Name	Cleared by DMA	Index in ICR to Program	Description
81	2B8 _H	OCU4	Yes	81	Output Compare Unit 4
82	2B4 _H	-	-	82	Reserved
83	2B0 _H	OCU6	Yes	83	Output Compare Unit 6
84	2AC _H	OCU7	Yes	84	Output Compare Unit 7
85	2A8 _H	-	-	85	Reserved
86	2A4 _H	-	-	86	Reserved
87	2A0 _H	-	-	87	Reserved
88	29C _H	-	-	88	Reserved
89	298 _H	FRT0	Yes	89	Free-Running Timer 0
90	294 _H	FRT1	Yes	90	Free-Running Timer 1
91	290н	FRT2	Yes	91	Free-Running Timer 2
92	28C _H	FRT3	Yes	92	Free-Running Timer 3
93	288 _H	RTC0	No	93	Real Time Clock
94	284 _H	CAL0	No	94	Clock Calibration Unit
95	280 _H	-	-	95	Reserved
96	27C _H	-	-	96	Reserved
97	278 _H	-	-	97	Reserved
98	274 _H	ADC0	Yes	98	A/D Converter 0
99	270 _H	-	-	99	Reserved
100	26C _H	-	-	100	Reserved
101	268 _H	-	-	101	Reserved
102	264 _H	-	-	102	Reserved
103	260 _H	-	-	103	Reserved
104	25C _H	-	-	104	Reserved
105	258 _H	LINR2	Yes	105	LIN USART 2 RX
106	254 _H	LINT2	Yes	106	LIN USART 2 TX
107	250 _H	-	-	107	Reserved
108	24C _H	-	-	108	Reserved
109	248 _H	-	-	109	Reserved
110	244 _H	-	-	110	Reserved
111	240 _H	-	-	111	Reserved
112	23C _H	-	-	112	Reserved
113	238 _H	-	-	113	Reserved
114	234 _H	-	-	114	Reserved
115	230 _H	LINR7	Yes	115	LIN USART 7 RX
116	22C _H	LINT7	Yes	116	LIN USART 7 TX
117	228 _H	LINR8	Yes	117	LIN USART 8 RX
118	224 _H	LINT8	Yes	118	LIN USART 8 TX
119	220 _H	-	-	119	Reserved
120	21C _H	-	-	120	Reserved
121	218 _H	-	-	121	Reserved



13.7 Turn on Sequence of Power Supply to A/D Converter and Analog Inputs

It is required to turn the A/D converter power supply (AV_{CC}, AVRH) and analog inputs (ANn) on after turning the digital power supply (V_{CC}) on.

It is also required to turn the digital power off after turning the A/D converter supply and analog inputs off. In this case, AVRH must not exceed AV_{CC} Input voltage for ports shared with analog input ports also must not exceed AV_{CC} (turning the analog and digital power supplies simultaneously on or off is acceptable)

13.8 Pin Handling when Not Using the A/D Converter

If the A/D converter is not used, the power supply pins for A/D converter should be connected such as $AV_{CC} = V_{CC} AV_{SS} = AVRH = V_{SS}$.

13.9 Notes on Power-on

To prevent malfunction of the internal voltage regulator, supply voltage profile while turning the power supply on should be slower than $50\mu s$ from 0.2V to 2.7V.

13.10Stabilization of Power Supply Voltage

If the power supply voltage varies acutely even within the operation safety range of the V_{CC} power supply voltage, a malfunction may occur. The V_{CC} power supply voltage must therefore be stabilized. As stabilization guidelines, the power supply voltage must be stabilized in such a way that V_{CC} ripple fluctuations (peak to peak value) in the commercial frequencies (50Hz to 60Hz) fall within 10% of the standard V_{CC} power supply voltage and the transient fluctuation rate becomes $0.1V/\mu s$ or less in instantaneous fluctuation for power supply switching.

13.11 Serial Communication

There is a possibility to receive wrong data due to noise or other causes on the serial communication.

Therefore, design a printed circuit board so as to avoid noise.

Consider receiving of wrong data when designing the system. For example apply a checksum and retransmit the data if an error occurs.

13.12Mode Pin (MD)

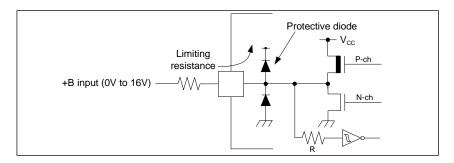
Connect the mode pin directly to Vcc or Vss pin. To prevent the device unintentionally entering test mode due to noise, lay out the printed circuit board so as to minimize the distance from the mode pin to Vcc or Vss pin and provide a low-impedance connection.

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- Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the VCC pin, and this may affect other devices.
- Note that if a +B signal is input when the microcontroller power supply is off (not fixed at 0V), the power supply is provided from the pins, so that incomplete operation may result.
- Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the Power reset.
- The DEBUG I/F pin has only a protective diode against VSS. Hence it is only permitted to input a negative clamping current (4mA). For protection against positive input voltages, use an external clamping diode which limits the input voltage to maximum 6.0V.

Sample recommended circuits:



[5]: The maximum permitted power dissipation depends on the ambient temperature, the air flow velocity and the thermal conductance of the package on the PCB.

The actual power dissipation depends on the customer application and can be calculated as follows:

 $P_D = P_{IO} + P_{INT}$

 $P_{IO} = \Sigma (V_{OL} \times I_{OL} + V_{OH} \times I_{OH})$ (I/O load power dissipation, sum is performed on all I/O ports)

 $P_{INT} = V_{CC} \times (I_{CC} + I_A)$ (internal power dissipation)

 I_{CC} is the total core current consumption into V_{CC} as described in the "DC characteristics" and depends on the selected operation mode and clock frequency and the usage of functions like Flash programming.

IA is the analog current consumption into AVCC.

- [6]: Worst case value for a package mounted on single layer PCB at specified TA without air flow.
- [7]: Write/erase to a large sector in flash memory is warranted with T_A ≤ + 105°C.

WARNING:

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.



14.2 Recommended Operating Conditions

 $(V_{SS} = AV_{SS} = 0V)$

Dougranatan	Courselle and	Value			1114			
Parameter	Symbol	Min	Тур	Max	Unit	Remarks		
Power supply voltage	\/ ^\/	2.7	-	5.5	V			
Fower supply voltage	V_{CC} , AV_{CC}	2.0	-	5.5	V	Maintains RAM data in stop mode		
Smoothing capacitor at C pin	Cs	0.5	1.0 to 3.9	4.7	μF	1.0µF (Allowance within ± 50%) 3.9µF (Allowance within ± 20%) Please use the ceramic capacitor or the capacitor of the frequency response of this level. The smoothing capacitor at V _{CC} must use the one of a capacity value that is larger than C _S .		

WARNING:

The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure. No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

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14.3 DC Characteristics

14.3.1 Current Rating

 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}C \text{ to } + 125^{\circ}C)$

cc = AVcc = 2.7V	Symbol Pin Conditions			Value		11	Demonde	
Parameter	Symbol	Name	Conditions	Min	Тур	Max	Unit	Remarks
			PLL Run mode with CLKS1/2 =	-	25	1	mA	T _A = +25°C
	I _{CCPLL}		CLKB = CLKP1/2 = 32MHz Flash 0 wait (CLKRC and CLKSC stopped)	-	-	34	mA	T _A = +105°C
			(CERRC and CERSC Stopped)	-	-	35	mA	T _A = +125°C
			Main Run mode with CLKS1/2 = CLKB = CLKP1/2 = 4MHz	-	3.5	-	mA	T _A = +25°C
	I _{CCMAIN}		Flash 0 wait (CLKPLL, CLKSC and CLKRC	-	-	7.5	mA	T _A = +105°C
			stopped)	-	-	8.5	mA	T _A = +125°C
Power supply current in Run modes ^[1]			RC Run mode with CLKS1/2 = CLKB = CLKP1/2 = CLKRC =	-	1.7	-	mA	T _A = +25°C
	I _{CCRCH}	Vcc	2MHz Vcc Flash 0 wait (CLKMC, CLKPLL and CLKSC	-	-	5.5	mA	T _A = +105°C
			stopped)	-	-	6.5	mA	T _A = +125°C
		RC Run mode with CLKS1/2 = CLKB = CLKP1/2 = CLKRC =	-	0.15	-	mA	T _A = +25°C	
	I _{CCRCL}		100kHz Flash 0 wait (CLKMC, CLKPLL and CLKSC	-	-	3.2	mA	T _A = +105°C
			stopped)	-	-	4.2	mA	T _A = +125°C
			Sub Run mode with CLKS1/2 = CLKB = CLKP1/2 = 32kHz	-	0.1	-	mA	T _A = +25°C
	I _{CCSUB}		Flash 0 wait (CLKMC, CLKPLL and CLKRC		-	3	mA	T _A = +105°C
			stopped)	-	-	4	mA	T _A = +125°C



14.3.2 Pin Characteristics

 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}\text{C to } + 125^{\circ}\text{C})$

			0V, I _A = - 40°C to +		Value			_
Parameter	Symbol	Pin Name	Conditions	Min	Тур	Max	Unit	Remarks
		5	-	V _{cc} ×0.7	-	V _{CC} + 0.3	V	CMOS Hysteresis input
"H" level input voltage	V _{IH}	Port inputs Pnn_m	-	V _{CC} ×0.8	-	V _{CC} + 0.3	٧	AUTOMOTIVE Hysteresis input
	V _{IHX0S}	X0	External clock in "Fast Clock Input mode"	VD×0.8	-	VD	V	VD=1.8V±0.15V
	V _{IHX0AS}	X0A	External clock in "Oscillation mode"	V _{CC} ×0.8	-	V _{CC} + 0.3	٧	
	V_{IHR}	RSTX	-	V _{CC} ×0.8	-	V _{CC} + 0.3	V	CMOS Hysteresis input
	V_{IHM}	MD	-	V _{CC} - 0.3	-	V _{cc} + 0.3	V	CMOS Hysteresis input
	V _{IHD}	DEBUG I/F	-	2.0	-	V _{CC} + 0.3	V	TTL Input
			-	V _{SS} - 0.3	_	V _{cc} ×0.3	V	CMOS Hysteresis input
	V _{IL}	Port inputs Pnn_m	-	V _{SS} - 0.3	-	V _{CC} ×0.5	V	AUTOMOTIVE Hysteresis input
"L" level input	V _{ILX0S}	Х0	External clock in "Fast Clock Input mode"	V _{SS}	-	VD×0.2	V	VD=1.8V±0.15V
voltage	V _{ILX0AS}	X0A	External clock in "Oscillation mode"	V _{SS} - 0.3	-	V _{CC} ×0.2	V	
	V_{ILR}	RSTX	-	V _{SS} - 0.3	-	V _{CC} ×0.2	V	CMOS Hysteresis input
	V _{ILM}	MD	-	V _{SS} - 0.3	-	V _{SS} + 0.3	V	CMOS Hysteresis input
	V_{ILD}	DEBUG I/F	-	V _{SS} - 0.3	-	0.8	V	TTL Input
"H" level output voltage	V _{OH4}	4mA type	$I_{OH} = -4mA$ $I_{OH} = -4mA$ $I_{OH} = -1.5mA$	V _{cc} - 0.5	-	Vcc	V	
"L" level	V _{OL4}	4mA type	$4.5V \le V_{CC} \le 5.5V$ $I_{OL} = +4mA$ $2.7V \le V_{CC} < 4.5V$ $I_{OL} = +1.7mA$		-	0.4	V	
	V _{OLD}	DEBUG I/F	$V_{CC} = 2.7V$ $I_{OL} = +25mA$	0	-	0.25	V	
Input leak current	I _{IL}	Pnn_m	$V_{SS} < V_I < V_{CC}$ $AV_{SS} < V_I < AV_{CC}$, AVRH	- 1	-	+ 1	μA	
Pull-up resistance value	R _{PU}	Pnn_m	V _{CC} = 5.0V ±10%	25	50	100	kΩ	_
Input capacitance	C _{IN}	Other than C, Vcc, Vss, AVcc, AVss, AVRH	-	-	5	15	pF	



14.4.3 Built-in RC Oscillation Characteristics

($V_{CC} = AV_{CC} = 2.7V$ to 5.5V, $V_{SS} = AV_{SS} = 0V$, $T_A = -40$ °C to + 125°C)

			Value				
Parameter	Symbol	Min	Тур	Max	Unit	Remarks	
Clock frequency	f _{RC}	50	100	200	kHz	When using slow frequency of RC oscillator	
Clock frequency	IRC	1	2	4	MHz	When using fast frequency of RC oscillator	
	trcstab	80	160	320	μs	When using slow frequency of RC oscillator (16 RC clock cycles)	
RC clock stabilization time		64	128	256	μ\$	When using fast frequency of RC oscillator (256 RC clock cycles)	

14.4.4 Internal Clock Timing

 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}C \text{ to } + 125^{\circ}C)$

Parameter	Comple of	Va	11-14		
Parameter	Symbol	Min	Max	Unit	
Internal System clock frequency (CLKS1 and CLKS2)	f _{CLKS1} , f _{CLKS2}	-	54	MHz	
Internal CPU clock frequency (CLKB), Internal peripheral clock frequency (CLKP1)	f _{CLKB} , f _{CLKP1}	-	32	MHz	
Internal peripheral clock frequency (CLKP2)	f _{CLKP2}	-	32	MHz	

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14.4.8 USART Timing

 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}C \text{ to } + 125^{\circ}C, C_L = 50pF)$

Parameter	Symbol	Pin name	Conditions	4.5V ≤ Vcc <	5V ≤ Vcc <5.5V		2.7V ≤ V _{CC} <4.5V	
Farameter	Symbol	Fill flame	Pin name Conditions		Max	Min	Max	t
Serial clock cycle time	t _{SCYC}	SCKn		4t _{CLKP1}	-	4t _{CLKP1}	-	ns
SCK ↓ →SOT delay time	t _{SLOVI}	SCKn, SOTn		- 20	+ 20	- 30	+ 30	ns
SOT → SCK ↑ delay time	t _{ovshi}	SCKn, SOTn	Internal shift clock	N×tclkp1- 20*	-	N×t _{CLKP1} -30*	-	ns
SIN → SCK ↑ setup time	t _{IVSHI}	SCKn, SINn	mode	t _{CLKP1} + 45	-	tclkp1 + 55	-	ns
$SCK \uparrow \rightarrow SIN \text{ hold time}$	t _{SHIXI}	SCKn, SINn		0	-	0	-	ns
Serial clock "L" pulse width	t _{SLSH}	SCKn		tclkp1+ 10	-	t _{CLKP1} + 10	-	ns
Serial clock "H" pulse width	t _{SHSL}	SCKn		t _{CLKP1} + 10	-	t _{CLKP1} + 10	-	ns
$SCK \downarrow \rightarrow SOT$ delay time	t _{SLOVE}	SCKn, SOTn	External	-	2t _{CLKP1} + 45	-	2tclkp1 + 55	ns
SIN → SCK ↑ setup time	t _{IVSHE}	SCKn, SINn	shift clock mode	t _{CLKP1} /2+ 10	-	t _{CLKP1} /2 + 10	-	ns
$SCK \uparrow \rightarrow SIN \text{ hold time}$	t _{SHIXE}	SCKn, SINn		tclkp1+ 10	-	t _{CLKP1} + 10	-	ns
SCK fall time	t _F	SCKn		-	20	-	20	ns
SCK rise time	t _R	SCKn		-	20	-	20	ns

Notes:

- AC characteristic in CLK synchronized mode
- C_L is he load capacity value of pins when testing.
- Depending on the used machine clock frequency, the maximum possible baud rate can be limited by some parameters.
 These parameters are shown in "CY96600 series HARDWARE MANUAL".
- t_{CLKP1} indicates the peripheral clock 1 (CLKP1), Unit: ns These characteristics only guarantee the same relocate port number.

For example, the combination of SCKn and SOTn_R is not guaranteed.

- *: Parameter N depends on tscyc and can be calculated as follows:
- If $t_{SCYC} = 2 \times k \times t_{CLKP1}$, then N = k, where k is an integer > 2
- If $t_{SCYC} = (2 \times k + 1) \times t_{CLKP1}$, then N = k + 1, where k is an integer > 1 Examples:

tscyc	N
4 xtclkp1	2
5 xtclkp1, 6 xtclkp1	3
7 xtclkp1, 8 xtclkp1	4

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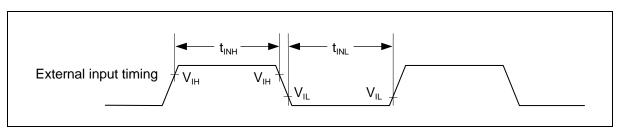


14.4.9 External Input Timing

 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}C \text{ to } + 125^{\circ}C)$

0000							
		B: N	Value				
Parameter	Symbol	Pin Name	Min	Max	Unit	Remarks	
Input pulse width		Pnn_m				General Purpose I/O	
	t _{INH} , t _{INL}	ADTG_R	2t _{CLKP1} +200 (t _{CLKP1} =1/f _{CLKP1})*	-	ns	A/D Converter trigger input	
		TINn				Reload Timer	
		TTGn				PPG trigger input	
		INn				Input Capture	
		AlNn, BlNn, ZlNn				Quadrature Position/Revolutior Counter	
		INTn, INTn_R, INTn_R1	200	-	- ns	External Interrupt	
		NMI				Non-Maskable Interrupt	

^{*:} tclkP1 indicates the peripheral clock1 (CLKP1) cycle time except stop when in stop mode.





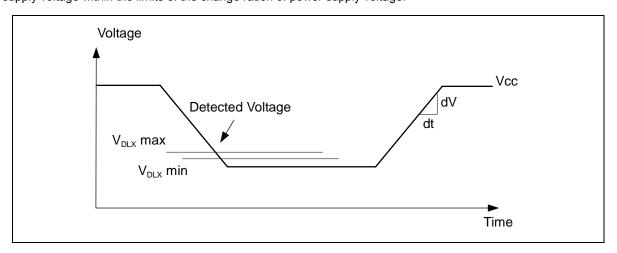
14.6 Low Voltage Detection Function Characteristics

 $(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}C \text{ to } + 125^{\circ}C)$

D		Conditions	Value			
Parameter	Symbol		Min	Тур	Max	Unit
	V_{DL0}	CILCR:LVL = 0000 _B	2.70	2.90	3.10	V
	V _{DL1}	CILCR:LVL = 0001 _B	2.79	3.00	3.21	V
	V _{DL2}	CILCR:LVL = 0010 _B	2.98	3.20	3.42	V
Detected voltage ^[1]	V _{DL3}	CILCR:LVL = 0011 _B	3.26	3.50	3.74	V
	V_{DL4}	CILCR:LVL = 0100 _B	3.45	3.70	3.95	V
	V _{DL5}	CILCR:LVL = 0111 _B	3.73	4.00	4.27	V
	V _{DL6}	CILCR:LVL = 1001 _B	3.91	4.20	4.49	V
Power supply voltage change rate ^[2]	dV/dt	-	- 0.004	-	+ 0.004	V/µs
	V	CILCR:LVHYS=0	-	-	50	mV
Hysteresis width	V _{HYS}	CILCR:LVHYS=1	80	100	120	mV
Stabilization time	T _{LVDSTAB}	-	-	-	75	μs
Detection delay time	t _d	-	-	-	30	μs

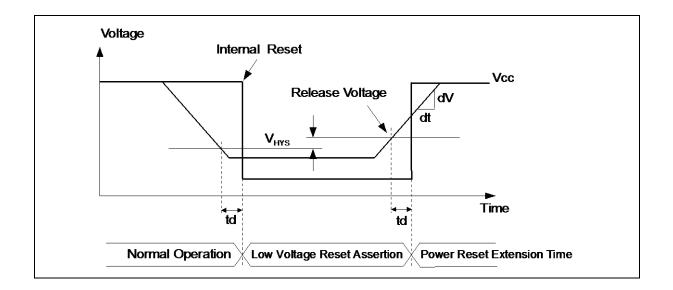
^{[1]:} If the power supply voltage fluctuates within the time less than the detection delay time (td), there is a possibility that the low voltage detection will occur or stop after the power supply voltage passes the detection range.

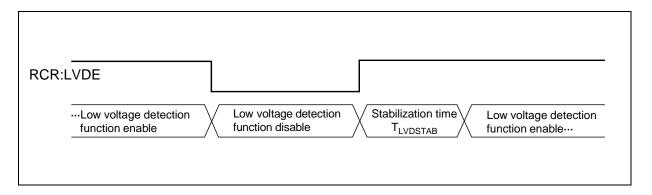
[2]: In order to perform the low voltage detection at the detection voltage (V_{DLX}), be sure to suppress fluctuation of the power supply voltage within the limits of the change ration of power supply voltage.



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18. Major Changes

Spansion Publication Number: MB96610 DS704-00007

pansion i	Publication Number: MB96610_DS704	-0000 <i>7</i>
Page	Section	Change Results
Revision 3	0	
	■FEATURES	Changed the description of "External Interrupts"
4		Interrupt mask and pending bit per channel
		Interrupt mask bit per channel
23 to 26	■HANDLING PRECAUTIONS	Added a section
	■ELECTRICAL CHARACTERISTICS	Changed the Conditions for I _{CCSRCH}
	3. DC Characteristics	CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 2MHz,
24	(1) Current Rating	CLKS1/2 = CLKP1/2 = CLKRC = 2MHz,
34		Changed the Conditions for I _{CCSRCL}
		CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 100kHz
		CLKS1/2 = CLKP1/2 = CLKRC = 100kHz
		Changed the Conditions for I _{CCTPLL}
		PLL Timer mode with CLKP1 = 32MHz
		PLL Timer mode with CLKPLL = 32MHz
		Changed the Value of "Power supply current in Timer modes"
		I _{CCTPLL}
		Typ: $2480\mu A \rightarrow 1800\mu A \ (T_A = +25^{\circ}C)$
0.5		Max: 2710 μ A \rightarrow 2245 μ A (T _A = +25°C)
35		Max: $3985\mu A \rightarrow 3165\mu A (T_A = +105^{\circ}C)$
		Max: $4830\mu A \rightarrow 3975\mu A (T_A = +125^{\circ}C)$
		Changed the Conditions for I _{CCTRCL}
		RC Timer mode with CLKRC = 100kHz,
		SMCR:LPMSS = 0 (CLKPLL, CLKMC and CLKSC stopped)
		RC Timer mode with CLKRC = 100kHz
		(CLKPLL, CLKMC and CLKSC stopped)
		Changed the annotation *2
		Power supply for "On Chip Debugger" part is not included.
36		Power supply current in Run mode does not include
		Flash Write / Erase current.
		The current for "On Chip Debugger" part is not included.
47	5. A/D Converter (2) Accuracy and Setting of the A/D Converter Sampling Time	Deleted the unit "[Min]" from approximation formula of Sampling time
	7. Flash Memory Write/Erase Characteristics	Changed the condition
52		$(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, VD=1.8V\pm0.15V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}\text{C to } + 125^{\circ}\text{C})$
		$(V_{CC} = AV_{CC} = 2.7V \text{ to } 5.5V, V_{SS} = AV_{SS} = 0V, T_A = -40^{\circ}\text{C to } + 125^{\circ}\text{C})$



Page	Section	Change Results
58	16. Ordering Information	Revised Marketing Part Numbers as follows: Before) MCU with CAN Controller MB96F612RBPMC-GS-E1 MB96F612RBPMC-GS-UJE1 MB96F612RBPMC-GS-UJE2 MB96F612RBPMC-GS-UJE2 MB96F613RBPMC-GSE1 MB96F613RBPMC-GSE1 MB96F613RBPMC-GS-UJE1 MB96F613RBPMC-GS-UJE2 MB96F613RBPMC-GS-UJE2 MB96F613RBPMC-GS-UJE2 MB96F615RBPMC-GSE1 MB96F615RBPMC-GSE1 MB96F615RBPMC-GSE1 MB96F615RBPMC-GS-UJE1 MB96F615RBPMC-GS-UJE2 MB96F615RBPMC-GS-UJE2 MB96F612ABPMC-GS-UJE2 MB96F612ABPMC-GSE1 MB96F612ABPMC-GSE1 MB96F612ABPMC-GS-UJE1 MB96F613ABPMC-GS-UJE2 MB96F613ABPMC-GS-UJE2 MB96F613ABPMC-GS-UJE1 MB96F613ABPMC-GS-UJE1 MB96F613ABPMC-GS-UJE1 MB96F613ABPMC-GS-UJE1 MB96F613ABPMC-GS-UJE1 MB96F613ABPMC-GS-UJE1 MB96F613ABPMC-GS-UJE1 MB96F613ABPMC-GS-UJE1 MB96F615ABPMC-GS-UJE1 MB96F615ABPMC-GS-UJE1 MB96F615ABPMC-GS-UJE1 MB96F615ABPMC-GS-UJE1 MB96F615ABPMC-GS-UJE1 MB96F615ABPMC-GSE2 MB96F615ABPMC-GS-UJE1
58	16. Ordering Information	After) MCU with CAN Controller CY96F612RBPMC-GS-UJE1 CY96F612RBPMC-GS-UJE2 CY96F613RBPMC-GS-UJE2 CY96F613RBPMC-GS-UJE2 CY96F613RBPMC-GS-UJERE2 CY96F615RBPMC-GS-UJE1 CY96F615RBPMC-GS-UJE2 CY96F615RBPMC-GS-UJE2 CY96F612ABPMC-GS-UJE1 CY96F612ABPMC-GS-UJE1 CY96F613ABPMC-GS-UJE1 CY96F613ABPMC-GS-UJE2 CY96F613ABPMC-GS-UJE2 CY96F613ABPMC-GS-UJE2 CY96F615ABPMC-GS-UJE2